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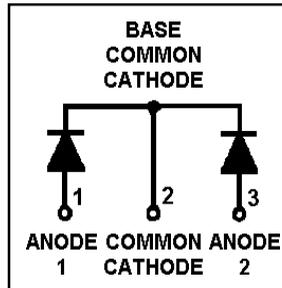
HFA70NC60C

HEXFRED™

Ultrafast, Soft Recovery Diode

Features

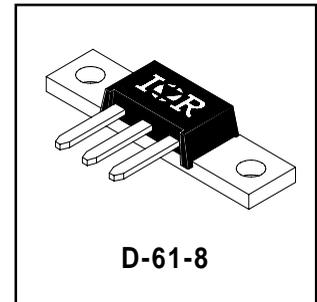
- Reduced RFI and EMI
- Reduced Snubbing
- Extensive Characterization of Recovery Parameters



$V_R = 600V$
$V_F(\text{typ.})^{\textcircled{3}} = 1.2V$
$I_{F(AV)} = 70A$
$Q_{rr}(\text{typ.}) = 210nC$
$I_{RRM}(\text{typ.}) = 6A$
$t_{rr}(\text{typ.}) = 30ns$
$di_{(rec)}/dt(\text{typ.})^{\textcircled{3}} = 180A/\mu s$

Description

HEXFRED™ diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.



Absolute Maximum Ratings (per Leg)

	Parameter	Max.	Units
V_R	Cathode-to-Anode Voltage	600	V
$I_F @ T_C = 25^\circ C$	Continuous Forward Current	56	A
$I_F @ T_C = 100^\circ C$	Continuous Forward Current	27	
I_{FSM}	Single Pulse Forward Current ①	200	
E_{AS}	Non-Repetitive Avalanche Energy ②	220	μJ
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	150	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	59	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ C$

Thermal - Mechanical Characteristics

	Parameter	Min.	Typ.	Max.	Units
R_{thJC}	Junction-to-Case, Single Leg Conducting	—	—	0.85	$^\circ C/W$ K/W
	Junction-to-Case, Both Legs Conducting	—	—	0.42	
R_{thCS}	Case-to-Sink, Flat , Greased Surface	—	0.30	—	
Wt	Weight	—	7.8 (0.28)	—	g (oz)
	Mounting Torque	35 (4.0)	—	50 (5.7)	lbf•in (N•m)

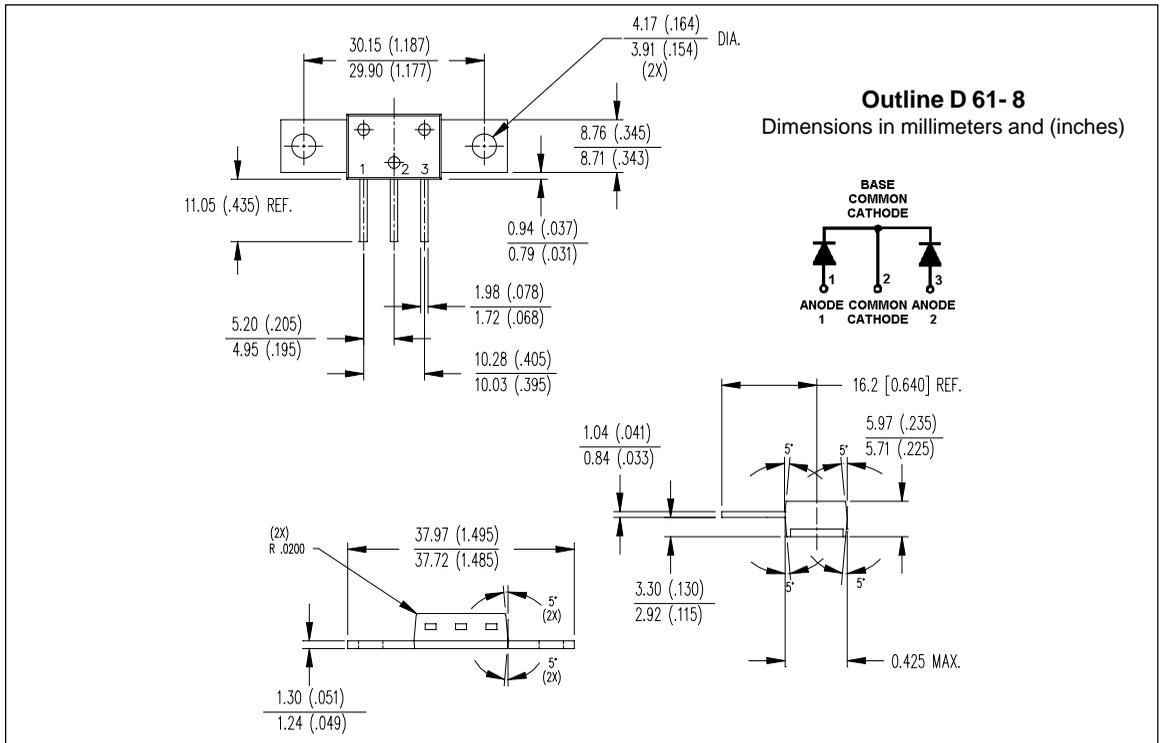
Note: ① Limited by junction temperature
 ② $L = 100\mu H$, duty cycle limited by max T_J
 ③ $125^\circ C$

Electrical Characteristics (per Leg) @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Min.	Typ.	Max.	Units	Test Conditions
V_{BR}	600	—	—	V	$I_R = 100\mu\text{A}$
V_{FM}	—	1.3	1.5	V	$I_F = 35\text{A}$
	—	1.5	1.7		$I_F = 70\text{A}$ See Fig. 1
	—	1.2	1.4		$I_F = 35\text{A}, T_J = 125^\circ\text{C}$
I_{RM}	—	2.0	10	μA	$V_R = V_R$ Rated
	—	0.50	2.0	mA	$T_J = 125^\circ\text{C}, V_R = 480\text{V}$ See Fig. 2
C_T	—	68	100	pF	$V_R = 200\text{V}$ See Fig. 3
L_S	—	5.5	—	nH	Lead to lead 5mm from package body

Dynamic Recovery Characteristics (per Leg) @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Min.	Typ.	Max.	Units	Test Conditions	
t_{rr}	—	30	—	ns	$I_F = 1.0\text{A}, di/dt = 200\text{A}/\mu\text{s}, V_R = 30\text{V}$	
t_{rr1}	—	70	110			$T_J = 25^\circ\text{C}$ See Fig.
t_{rr2}	—	115	180			$T_J = 125^\circ\text{C}$ 5
I_{RRM1}	—	6.0	11	A	$T_J = 25^\circ\text{C}$ See Fig.	
					$T_J = 125^\circ\text{C}$ 6	
I_{RRM2}	—	9.0	16	A	$T_J = 25^\circ\text{C}$ See Fig.	
					$T_J = 125^\circ\text{C}$ 7	
Q_{rr1}	—	210	580	nC	$T_J = 25^\circ\text{C}$ See Fig.	
					$T_J = 125^\circ\text{C}$ 8	
Q_{rr2}	—	520	1400	nC	$T_J = 25^\circ\text{C}$ See Fig.	
					$T_J = 125^\circ\text{C}$ 8	
$di_{(rec)M}/dt1$	—	280	—	A/ μs	$T_J = 25^\circ\text{C}$ See Fig.	
$di_{(rec)M}/dt2$	—	180	—			$T_J = 125^\circ\text{C}$ 8



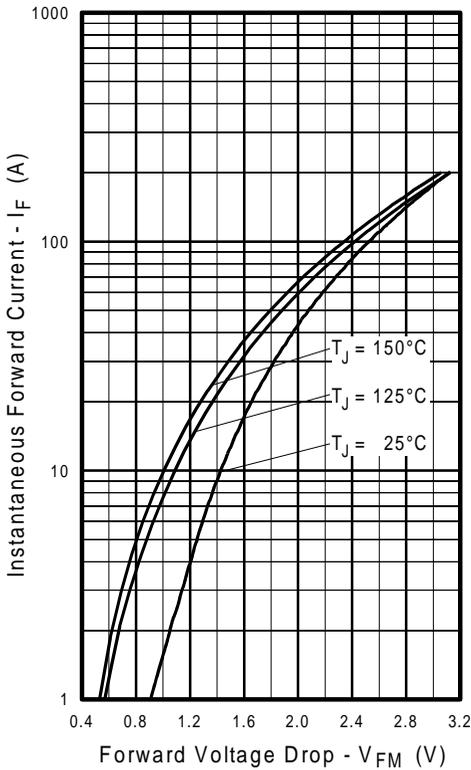


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current, (per Leg)

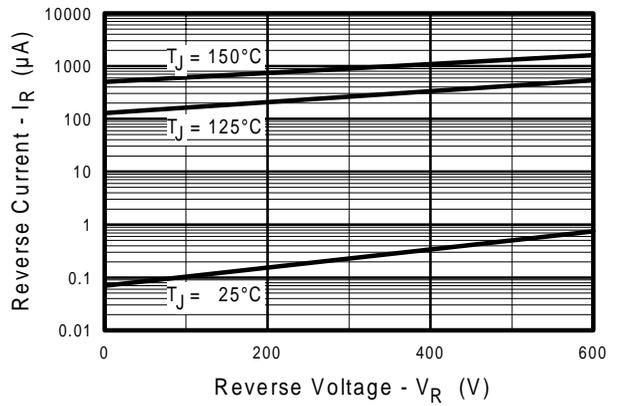


Fig. 2 - Typical Reverse Current vs. Reverse Voltage, (per Leg)

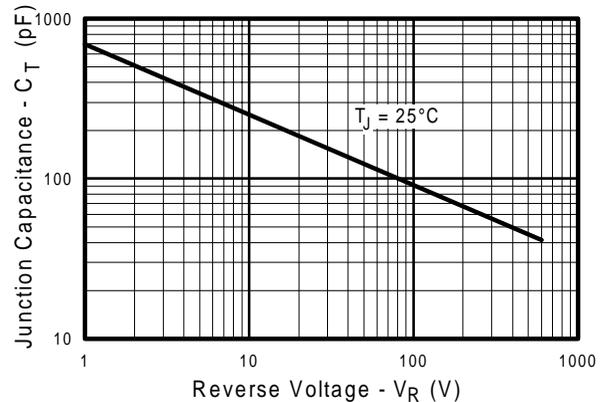


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage, (per Leg)

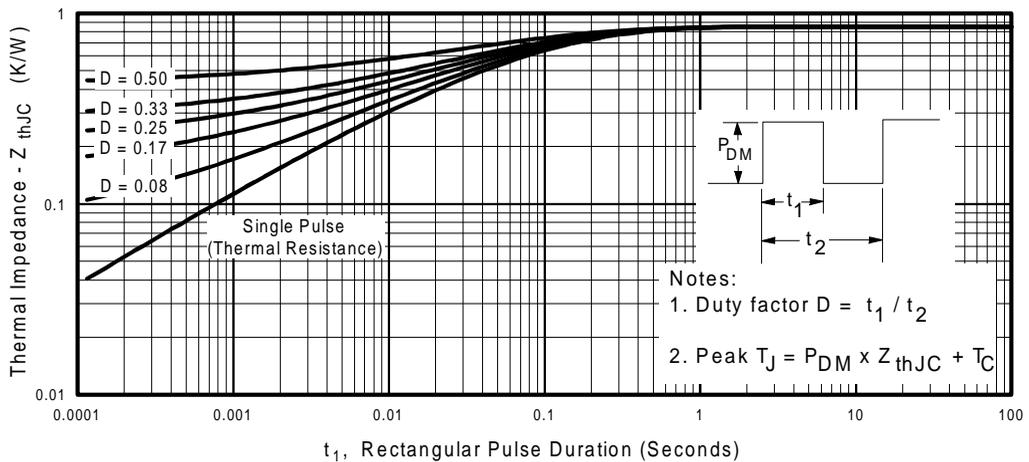


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics, (per Leg)

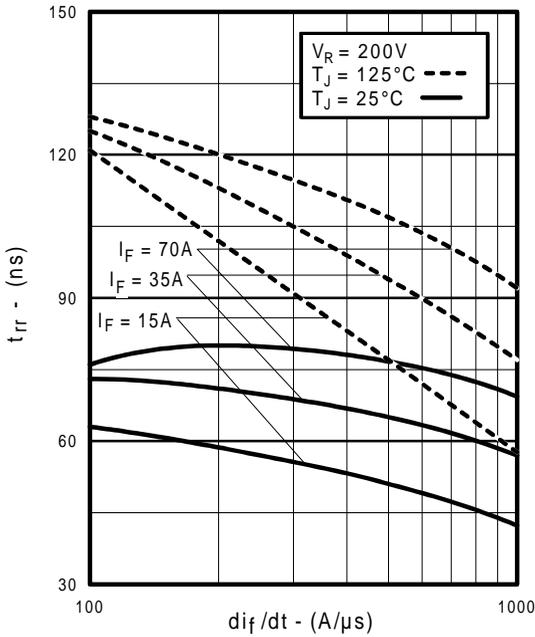


Fig. 5 - Typical Reverse Recovery vs. di_f/dt , (per Leg)

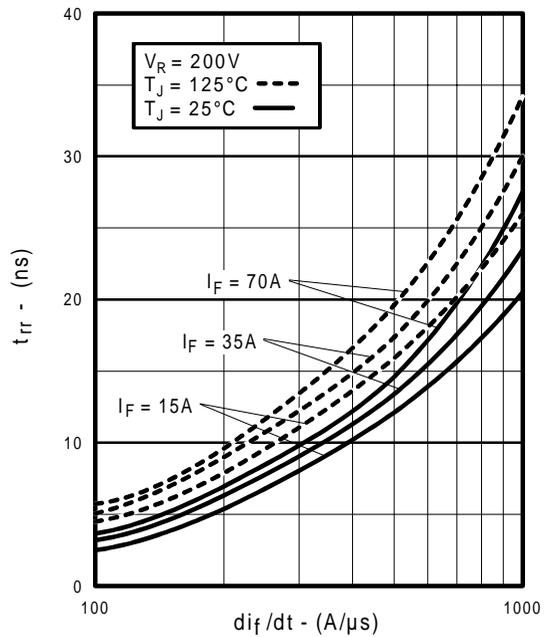


Fig. 6 - Typical Recovery Current vs. di_f/dt , (per Leg)

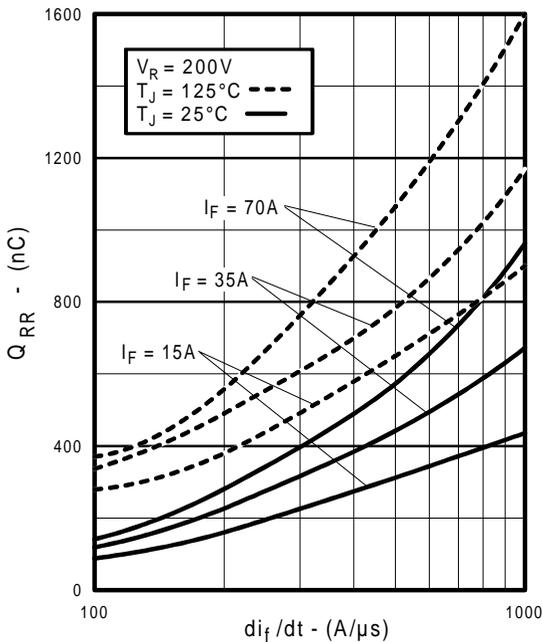


Fig. 7 - Typical Stored Charge vs. di_f/dt , (per Leg)

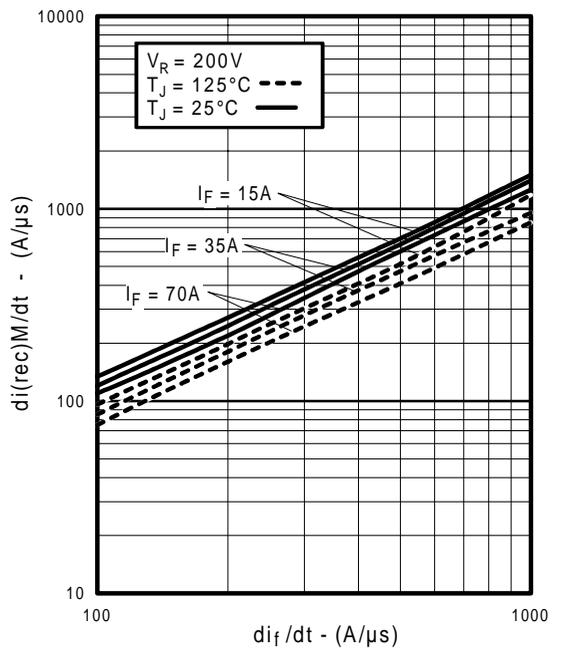


Fig. 8 - Typical $di_{(rec)}M/dt$ vs. di_f/dt , (per Leg)

REVERSE RECOVERY CIRCUIT

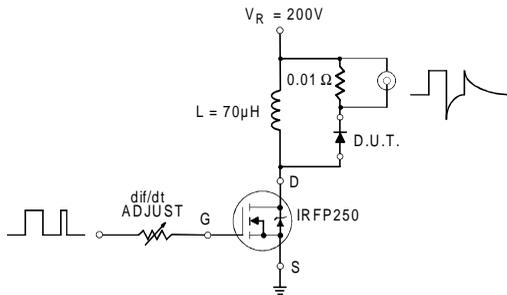
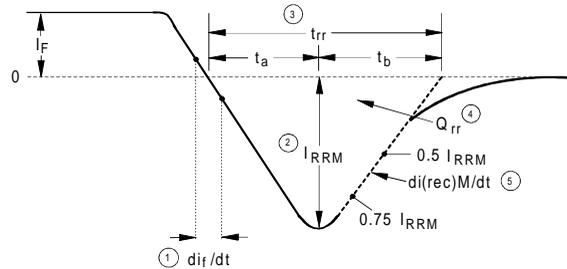


Fig. 9 - Reverse Recovery Parameter Test Circuit



1. di/dt - Rate of change of current through zero crossing
2. I_{RRM} - Peak reverse recovery current
3. t_{rr} - Reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current
4. Q_{rr} - Area under curve defined by t_{rr} and I_{RRM}
5. $di_{(rec)M}/dt$ - Peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 10 - Reverse Recovery Waveform and Definitions

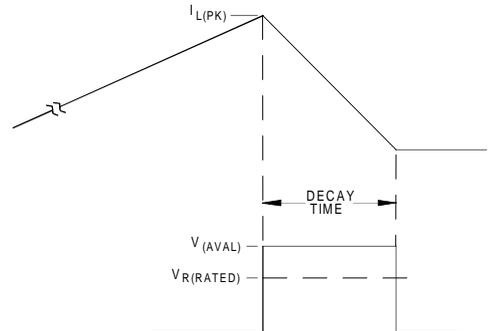
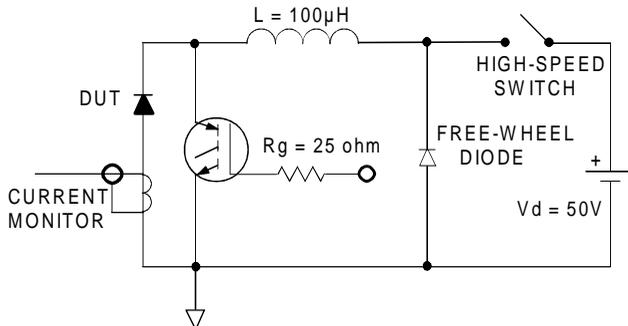


Fig. 11 - Avalanche Test Circuit and Waveforms